Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A leadframe-based housing for a surface-mountable electronic component, with a leadframe having a front side and a back side and comprising at least two electrical connector strips [[(2a, 2b)]], and an injection-molded or transfer-molded housing base body [[(8a, 8b)]] made from an electrically insulating injection compound and comprising a front portion disposed at the front side of said leadframe and a back wall disposed at the back side of said leadframe, ~~characterized in that~~ wherein said leadframe comprises at least one injection aperture [[(24)]] through which said housing base body is injected onto said leadframe from a back side of said leadframe.

2. (Currently Amended) The housing as described in claim 1, ~~characterized in that~~ wherein said injection aperture [[(24)]] is disposed in one of said electrical connector strips.

3. (Currently Amended) The housing as described in claim 1[[or 2]], wherein said back wall has a thickness of less than 0.3 mm and more than 0 mm.

4. (Currently Amended) The housing as described in ~~at least one of claims 1 to 3~~ claim 1 for a radiation-emitting and/or radiation-detecting component, wherein said housing base body [[(8a, 8b)]] comprises in said front portion [[(8a)]] a recess for receiving a radiation-emitting and/or radiation-detecting chip, said injection aperture [[(24)]] being disposed in the region of a wall of said front portion delimiting said recess.

5. (Original) The housing as described in claim 4, wherein said recess is formed as a reflector.

6. (Currently Amended) A leadframe ribbon comprising at least one housing as described in ~~one of claims 1 to 5~~ claim 1.

7. (Currently Amended) An electronic component having a housing as described in ~~at least one of claims 1 to 5~~ claim 1, which comprises at least one chip[[(16)]].

8. (Currently Amended) The electronic component as described in claim 7, wherein said at least one chip[[(16)]] is a radiation-emitting and/or radiation-detecting chip.

9. (Currently Amended) The electronic component as described in claim 7[[or 8]], wherein said chip[[(16)]] is disposed on one of the two connector strips[[(2a)]] and is electrically connected to the second connector strip[[(2b)]] by means of an electrical connecting line[[(17)]].

10. (Currently Amended) The electronic component as described in claim 7[[or 8]], wherein said chip[[(16)]] is disposed on a mounting area of said housing base body and is electrically connected to each of said electrical connector strips[[(2a, 2b)]] by means of in each case one electrical connecting line[[(17)]].

11. (Currently Amended) The electronic component as described in claim 7[[or 8]], wherein said chip[[(16)]] is disposed on a thermally well-conducting chip carrier leading through said housing base body to the back side and is electrically connected to each of said electrical connector strips[[(2a, 2b)]] by means of in each case one electrical connecting line [[(17)]].

12. (Currently Amended) The electronic component as described in ~~at least one of claims 8 to 11~~ claim 1, ~~comprising a housing with reference to claim 4 or 5,~~ wherein said recess is filled with an injection compound that is transparent to radiation emitted by and/or to be detected by said chip.

13. (Currently Amended) A method for producing a leadframe-based housing as described in ~~one of claims 1 to 5~~ claim 1, comprising the following method steps:

a) preparing said leadframe comprising said two connector strips and said injection aperture[[(24)]],

b) applying to said leadframe an injection mold that forms around said leadframe a cavity for creating said housing base body and inserting an injection nozzle into or placing it against said injection aperture[[(24)]],

c) injecting the injection compound into said cavity,

d) at least partially solidifying the injection compound, and

e) opening the injection mold, including the removal of said injection nozzle.

14. (Original) The method as described in claim 13, wherein a thermoplastic material is used as the injection compound.

15. (New) The electronic component comprising a housing with reference to claim 4, wherein said recess is filled with an injection compound that is transparent to radiation emitted by and/or to be detected by said chip.